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LI et al.(10) **Pub. No.: US 2022/0361328 A1**(43) **Pub. Date: Nov. 10, 2022**(54) **POWER CONVERSION MODULE USING
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(57)

ABSTRACT

Power conversion modules using compression mount technology (CMT) connectors and associated apparatus and methods. Assemblies include a CMT connector that includes an array of spring-loaded CMT pins or contacts that are configured to contact respective pads on a pair of printed circuit board (PCBs), such as for VR module card or power conversion module and a motherboard. The power conversion modules in combination with the CMT connectors provide several advantages, including, a common VR module/power conversion module/motherboard footprint across OEM platforms and test hardware, just in time VR module attachment for improved inventory management, removable power delivery solution makes the platform more conducive to debug, in field servicing, and platform upgradable for higher power CPU/GPU/XPU.

